

CMP ORDER FORM FOR ICs MANUFACTURING

version 11 February 2011

CMP RUN:

TOPCELL NAME:

PROCESS:

DELIVERY & INVOICING

CIRCUIT'S PURPOSE: Education Research Industry

INSTITUTION/COMPANY:

DELIVERY TO: Name:

Phone:

Institution/company:

Fax:

Full address (no PO box):

SPECIAL REQUEST ON DELIVERY: yes no

If no, circuits will be sent by courier service (UPS, DHL...) with our standard 'invoice for customs' for foreign countries.

INVOICE TO: Name:

VAT id:

E-mail:

(Europe only)

Institution/Company:

Fax:

Address:

Phone:

P.O. number:

CIRCUIT SIZE IN MICRONS:

DeltaX =

DeltaY =

NUMBER OF PARTS⁽¹⁾ Bare dies: Packaged:

PACKAGE:

Bonding diagram⁽²⁾: free imposed

ids: removable sealed

BULK MICROMACHINING⁽³⁾ yes no

COLOUR PLOTS: yes no number:

NON-STANDARD DIE THICKNESS⁽⁴⁾: μ

ADDITIONAL SERVICES⁽⁵⁾:

Reserved to CMP

area:

price:

price:

price:

price:

price:

price:

shipment:

Total:

By signing the present order form, the responsible person accepts the Terms and Conditions that are in <http://cmp.imag.fr/information/terms>

Name and signature of the responsible person:

Name:

date:

signature:

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TECHNICAL INFORMATION

TECHNICAL ENQUIRIES⁽⁶⁾: Name:

Phone:

E-mail:

Fax:

CIRCUIT TRANSFER: ftp E-mail tape CDROM

DESCRIPTION FORMAT⁽⁷⁾: GDSII CIF DEF CADENCE data base

CAD TOOL: version:

DESIGN KIT: version:

DRC VIOLATIONS: yes no *If you request DRC violations, please make a case overleaf.*

LIBRARY CELL REPLACEMENT REQUIRED⁽⁸⁾: yes no

(make a list of used libraries)

LIBRARY NAME

version

LOW VOLUME PRODUCTION EXPECTED? yes perhaps no

VERSION OF DESIGN THAT SHOULD BE PRODUCED: this one after test an improved one

START PRODUCTION: in next 6 months < 1 year > 1 year

EXPECTED NUMBER OF CIRCUITS: < 100 < 1000 < 10000 > 10000

CIRCUIT FUNCTION *(a few lines in English. Mandatory for non E.U. countries, used for export regulation. Mandatory for technologies of STMicroelectronics – Will be published in the CMP annual report)*

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DO NOT SEND THIS PAGE

RESERVATION REQUESTS

For technologies of STmicroelectronics you must send a reservation request **one month before the deadline**. Please contact us for the document.

PACKAGES

Packaging service is available if you are following packaging rules of CMP. Prices, list of packages and cavity maps are in:
<http://cmp.imag.fr -> PRODUCTS -> Packaging Assembly>
<http://cmp.imag.fr -> Packaging list and prices>

Contact us for unlisted ceramic packages, we will check with our subcontractors.

Contact us for plastic packages. Small sets of plastic packages are possible. Main packages are SOIC, SSOP, LPCC (leadless), QFP, PLCC and EDQUAD (thermal solution). **NB:** design your pad ring according to the chosen package. Packaging rules for plastic are more strict than the ones for ceramic packages.

NOTES

- (1) Default is 25 bare dies for our main technologies. Additional dies and packaging are charged.
- (2) Free means that CMP will make a bonding diagram and send it to you for approval. Note that CMP can't make bonding diagrams that doesn't match the packaging rules. If you send your bonding diagram please clearly identify pad 1 in your circuit (use lettering in a metal layer).
- (3) For micromechanical systems only.
- (4) Standard die thicknesses (T) are as following. You can request a smaller thickness for your application. Contact us for cost and delay. "T*" means that die thickness can't be changed.
austriamicrosystems: 0.35 μ : T= 480 μ
STMicroelectronics: 130nm: T= 375 μ 65nm: T=250 μ 40nm : T= 250 μ
- (5) If you need any other service, contact us to check if we can provide it.
- (6) The person given on the form under the heading "TECHNICAL ENQUIRIES" must be rapidly available for questions and corrections of the design. The designer is generally the best choice.
- (7) Main format is GDSII. You must contact CMP for agreement if you use another format.
- (8) Layout descriptions of library cells of STMicroelectronics contain only metal layers. For these technologies, library cells have to be replaced by the full layout version. **You must request replacement** and provide CMP with the list of used libraries and their versions.
NB: names of standard cells are reserved names. Using them for naming custom cell is forbidden otherwise custom cell will be overwritten by standard cell.
Example of request of "LIBRARY CELL REPLACEMENT" for a circuit in HCMOS9GP technology of STMicroelectronics:
IOLIB_65_M6_LL version 7.1
COR9GPLL version 4.1
DPHS9gp_1024x32m16d4_L version DPHS_100327_1
- (9) Standard is ftp, contact CMP to get an account and a password. Email transfer without an authorization from CMP is forbidden.